



SUSS MICROTEC INVESTOR PRESENTATION

March/April 2015

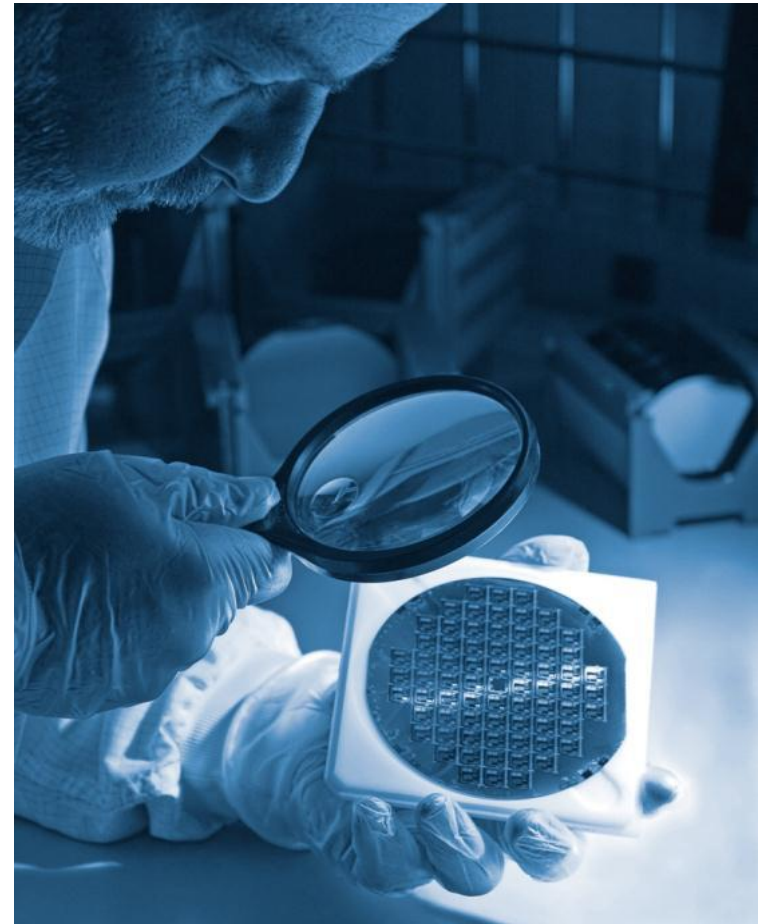
This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

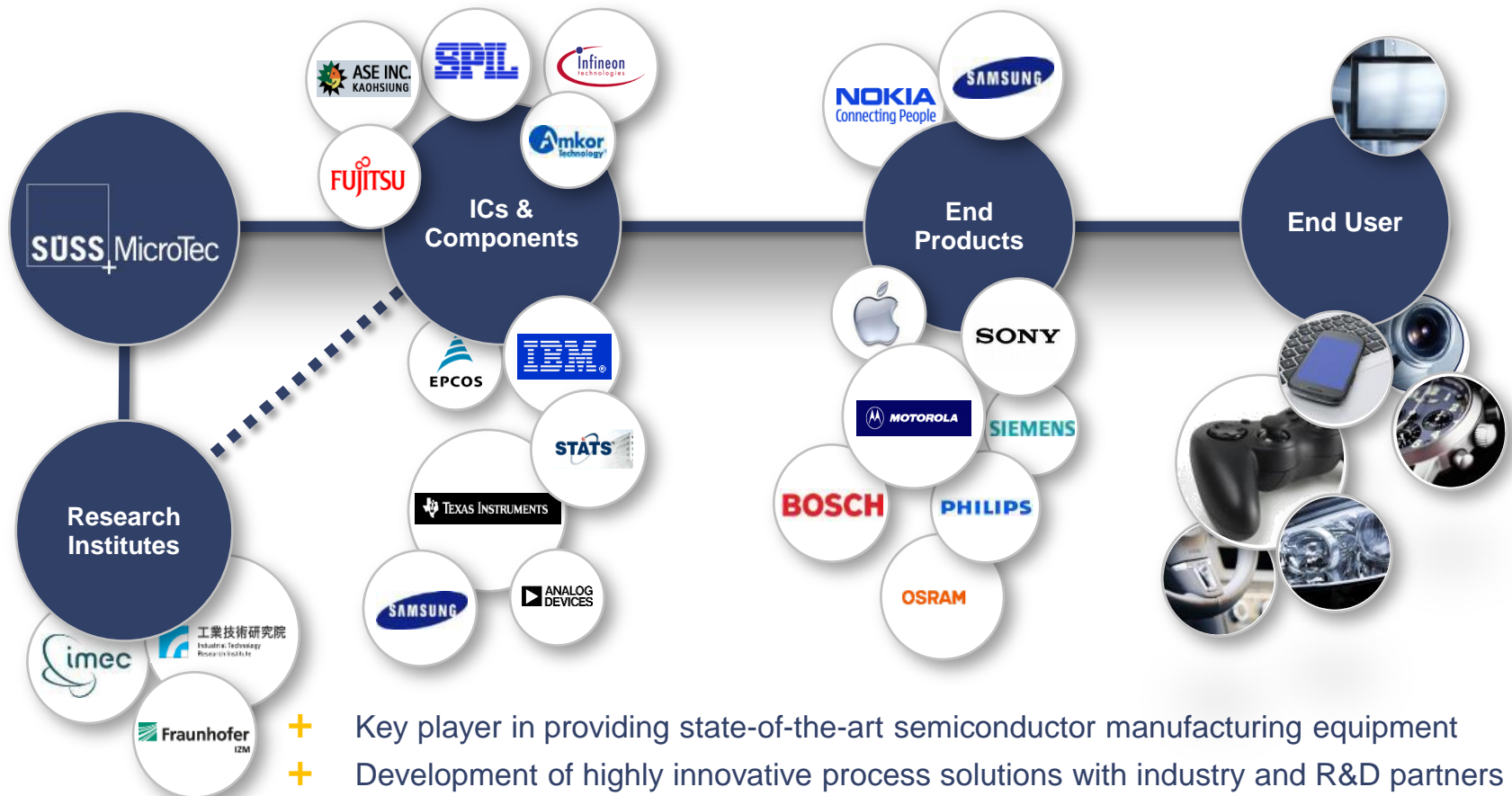
TABLE OF CONTENT



- I. SUSS MicroTec at a Glance**
- II. Products and Markets
- III. Growth Opportunities
- IV. Financials
- V. Outlook

- + A global leader in manufacturing equipment for the semiconductor mid- and backend market
 - + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
 - + Focus on attractive growth markets: Semiconductors, MEMS and LED
 - + Leading market position in target markets
-
- + Key figures 2014:
 - Order Entry € 134.3 million
 - Sales € 145.3 million
 - Employees: 659





- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Key components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 18.9 € million

Sales 21.5 € million

Employees 118

EUROPE

Order Entry 41.9 € million

Sales 42.7 € million

Employees 419

ASIA

Order Entry 67.6 € million

Sales 81.1 € million

Employees 122



*Figures refer to the fiscal year 2014

MAIN PRODUCTION SITES

Germany

Sternenfels*

- + Development/production:
 - Bonder
 - Coater and Developer
 - Photomask Equipment
- + Core competencies:
 - Wet processing
 - Wafer bonding
 - Photomask Equipment
- + Production facility ~15,000 m²



Garching*

- + SUSS MicroTec HQ
- + Development/production:
 - Mask Aligner
 - Bond Aligner
- + Core competencies:
 - Exposure (proximity exposure)
 - Alignment
 - Bond Aligner
- + Production facility ~9,000 m²



USA

Corona (California)

- + Development/production:
 - Stepper/Scanner
 - Laser Processing
- + Core competencies:
 - Exposure (UV projection)
 - Laser Ablation



*Production site is owned by SUSS MicroTec

TABLE OF CONTENT



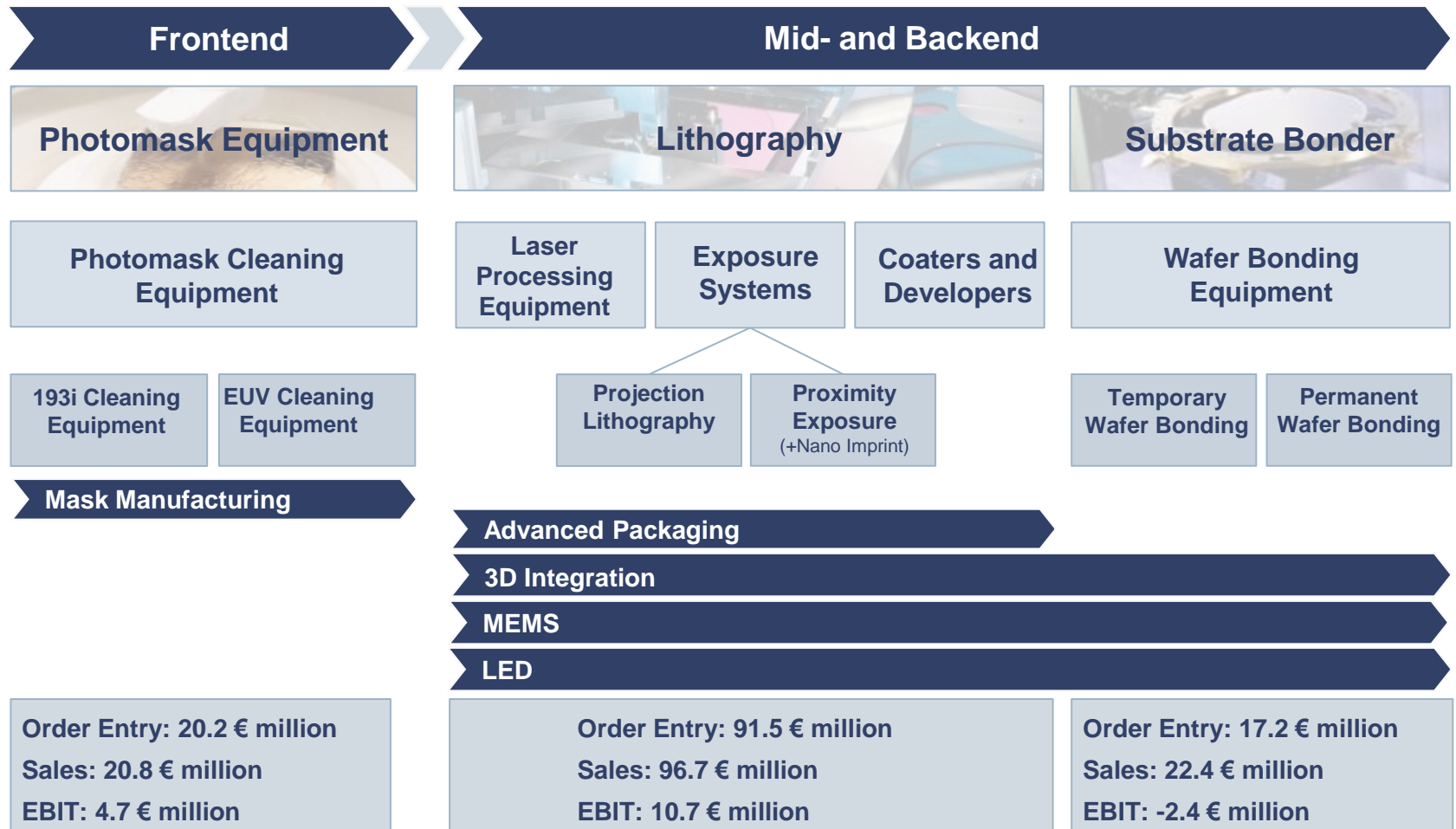
I. SUSS MicroTec at a Glance

II. **Products and Markets**

III. Growth Opportunities

IV. Financials

V. Outlook

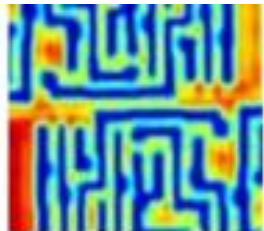


* EBIT Segment Others: -4.5 € million

Semiconductors

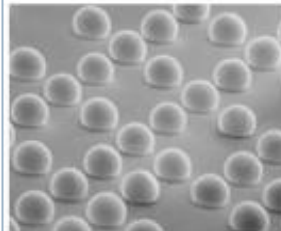
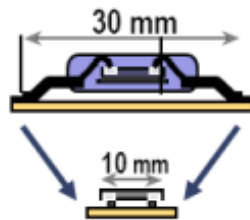
Mask Making

Photomask
Cleaning



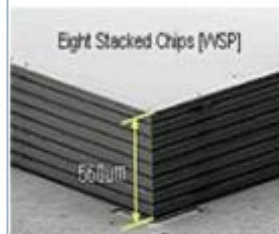
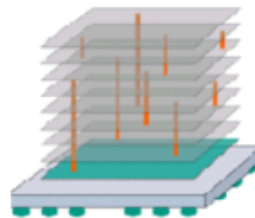
Advanced Packaging

Micro-Bumping



3D Integration

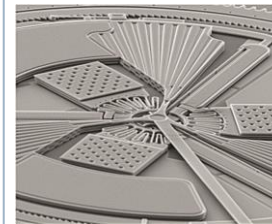
3D (TSV)
Stacking



Sensors

MEMS

Computing,
Automotive...



Lighting

LED

General Lighting,
HB and UHB

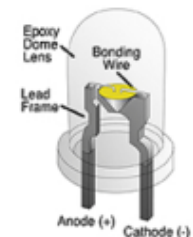


TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products and Markets

III. Growth Opportunities

IV. Financials

V. Outlook

Digital Lifestyle

- + The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- + Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- + New device generations offer higher functionality



E-Mobility

- + Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- + EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices and high performance ICs at the same time



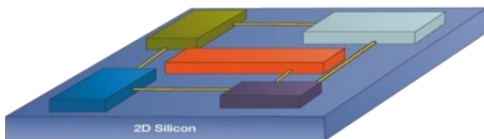
Energy Efficiency

- + Increased environmental awareness and rising energy cost drive the demand for energy efficient solutions i.e. solid state lighting
- + Energy efficiency in industrial production
- + Smart energy management in household applications



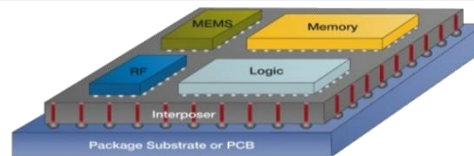
2D Packaging

- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size



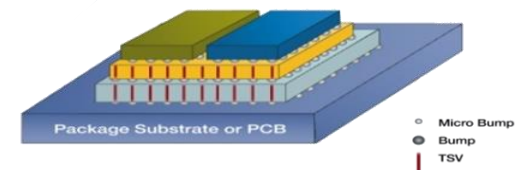
2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law



3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products and Markets

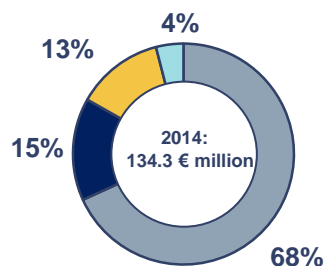
III. Growth Opportunities

IV. Financials

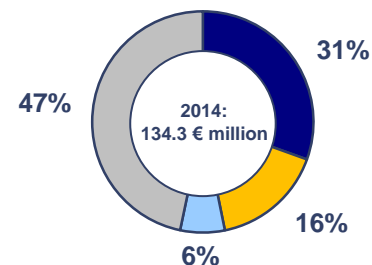
V. Outlook

ORDER ENTRY AND SALES BY SEGMENT AND REGION

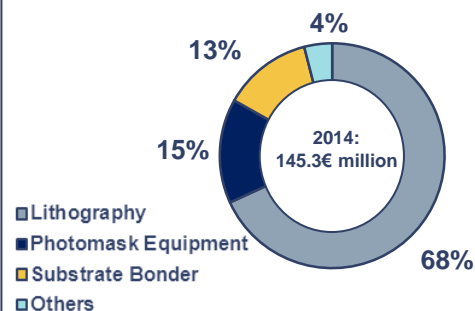
Order Entry by Segment



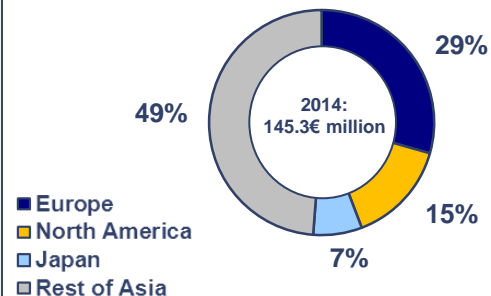
Order Entry by Region



Sales by Segment

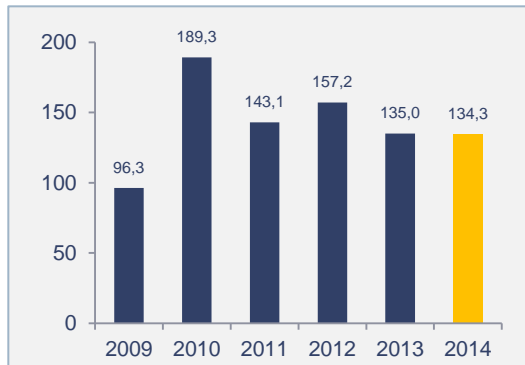


Sales by Region

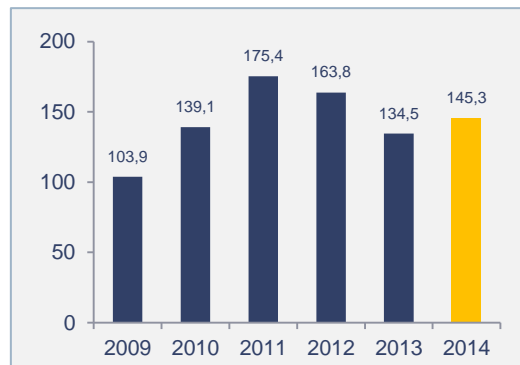


LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

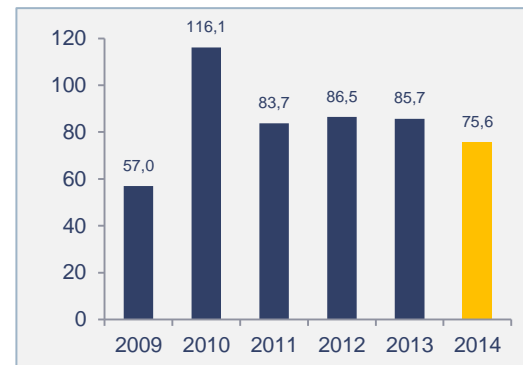
Order Entry in € million



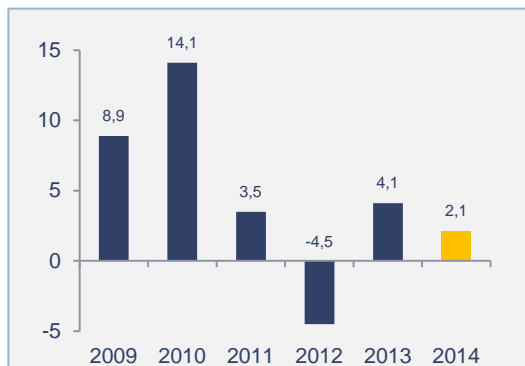
Sales in € million



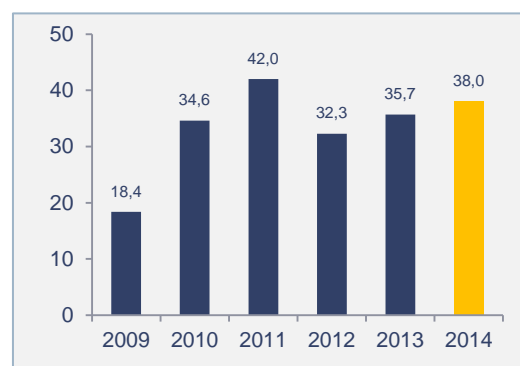
Order backlog in € million



Free Cash Flow in € million



Net cash in € million



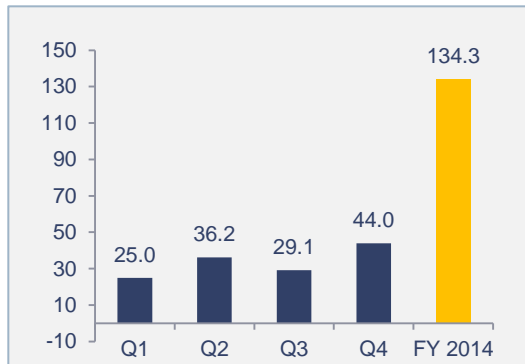
EBIT in € million



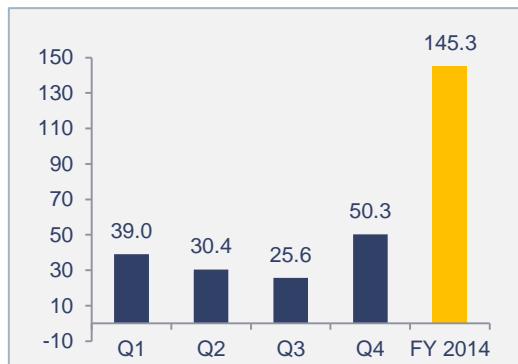
* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

2014 - P&L KEY FIGURES BY QUARTER

Order Entry in € million



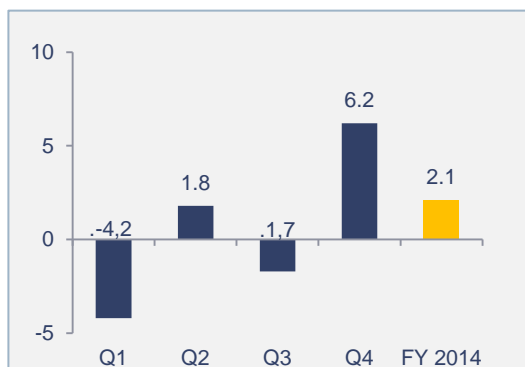
Sales in € million



Order backlog in € million



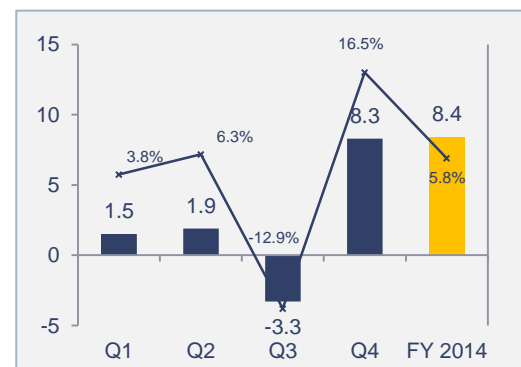
Free Cash Flow in € million



Net cash in € million



EBIT in € million



* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

KEY FINANCIALS

in € million	2014	2013	in %
Order Intake	134.3	135.0	-0.5%
Order Backlog 12/31	75.6	85.7	-11.8%
Revenue	145.3	134.5	+8.1%
EBIT	8.4	-19.4	--
<i>EBIT in % of Sales</i>	<i>5.8%</i>	<i>-14.4%</i>	<i>--</i>
Earnings after tax	8.2	-16.0	--
EPS in €	0.24	-0.84	--
Net Cash*	38.0	35.7	+6.4%
Free Cash Flow**	2.1	4.1	-48.8%
Employees 12/31	659	655	-0.6%

* incl. stock of interest-bearing securities

**before consideration of purchased interest-bearing securities

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products and Markets

III. Growth Opportunities

IV. Financials

V. Outlook

Lithography	Mask Aligner and Coaters /Developers: Current and expected sales level around 80 – 90 € million per year UV Projection Scanners and Laser Ablation Steppers: Current annual sales at around 10 € million
Photomask Equipment	Stable sales level at around 20 € million per year
Substrate Bonders	Permanent Bonding and Temporary Bonding: Expected sales level of the division: 15 – 20 € million
Guidance	FY 2015: Sales: 130 to 140 € million EBIT: break-even Q1 2015: Order Intake: 25 - 35 € million

Business Environment/Targets

- + Enabling „Moore’s Law“ and „More than Moore“
- + Fundamental growth in target markets
- + Leveraging the existing technologies and core competencies into products
- + Grow revenue in the Lithography segment and bring the core business back to its former strength
- + Position SUSS MicroTec Photonic systems tools in the market and grow revenue
- + Generate a positive EBIT in the Substrate Bonder Division

Balance Sheet and P&L

- + (Maintain) tight cost structure
- + Strong financial position and positive free cash flow
- + Equity ratio > 60%
- + Target gross margins:
short-term 33 – 35%
medium-term >35%
- + Medium-term EBIT-margin of 5%+



Thank you!

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www.SUSS.com

Management Board

Michael Knopp, CFO (Speaker)



Finance, Tax, Legal, HR, IT,
Sales, Service & Marketing,
Strategy, Investor Relations

Walter Braun, COO



Operations, Quality, Supply Chain
Management, R & D, Patents,
Environmental Protection, Work
Safety, Strategy

Divisions

Lithography

Photomask Equipment

Bonder

Sales & Service

Europe, USA, Japan, China, Taiwan, Singapore, Korea

Contact

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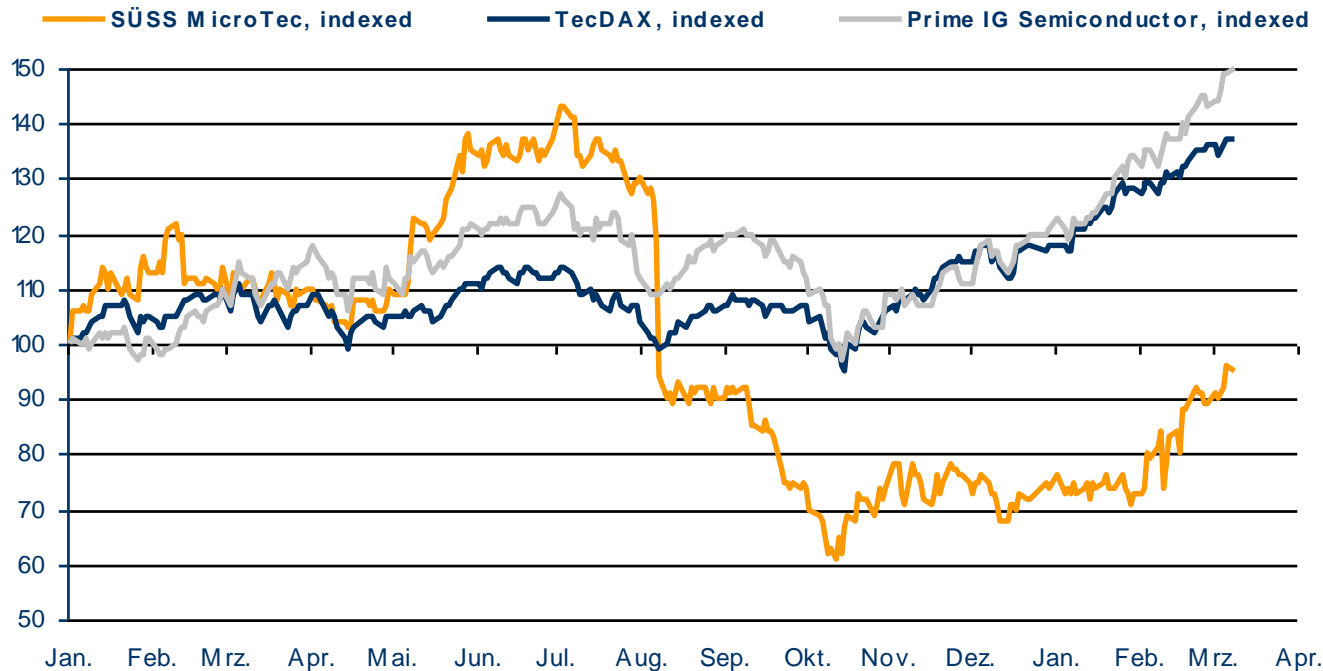
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Germany
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Financial Calendar 2015

KeplerCheuvreux Investment Conference, Frankfurt	19 Jan
Annual Report 2014	30 Mar
Quarterly Report 2015	8 May
Annual General Meeting 2015, Munich	2 Jun
Interim Report 2015	6 Aug
Nine-month Report 2015	5 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2014: 6.38 €)

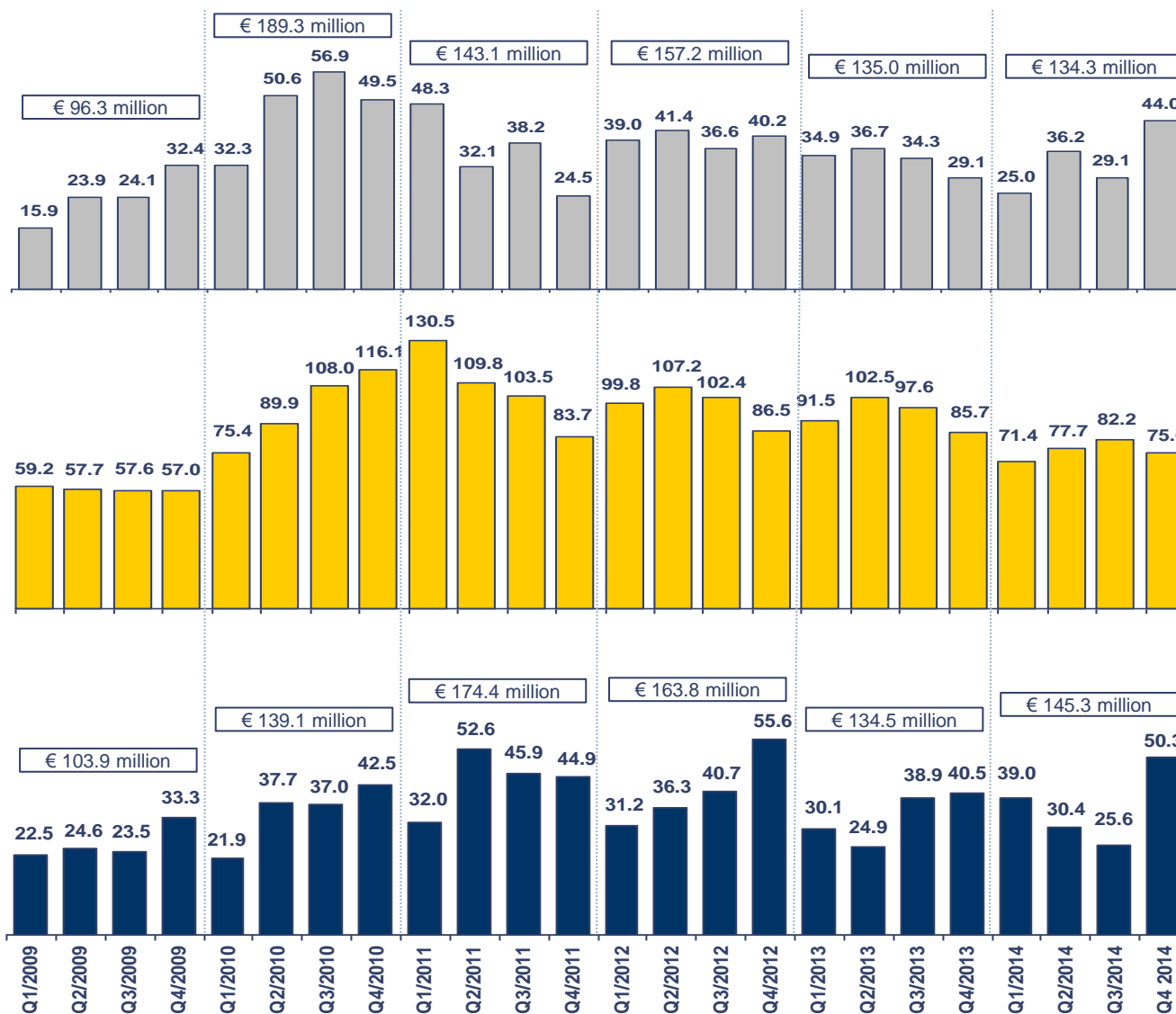


Major Shareholders:

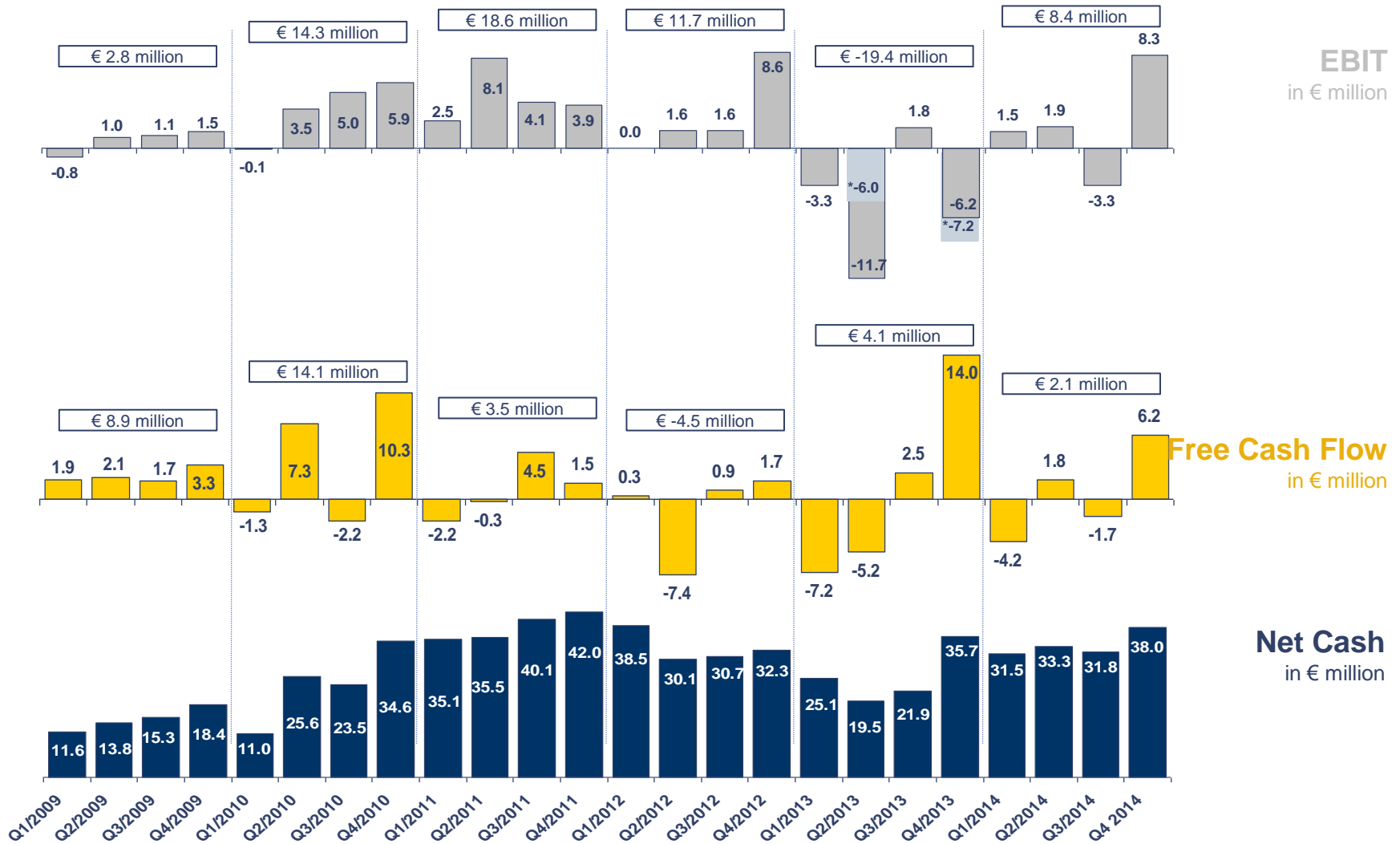
Henderson	5.13%
Universal	5.04%
ING Invest	3.42%
Sycomore	3.14%
Baillie Gifford	3.00%

Average daily trading volume January 2014 – March 2015: ~ 121,000

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding

